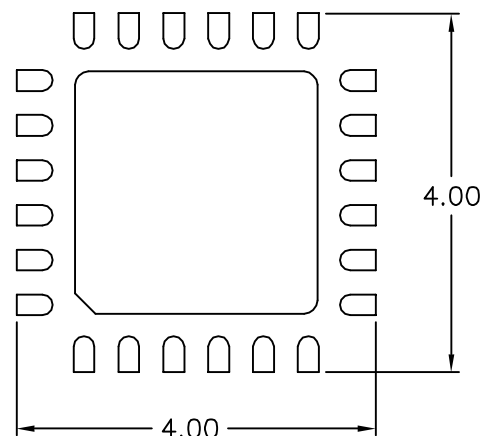
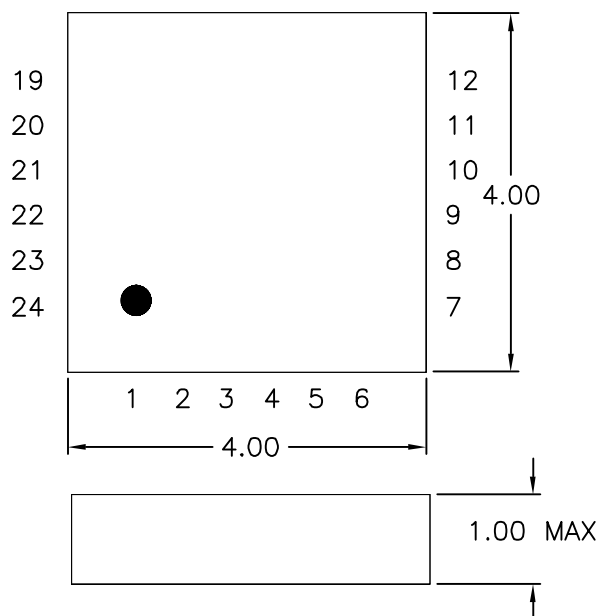


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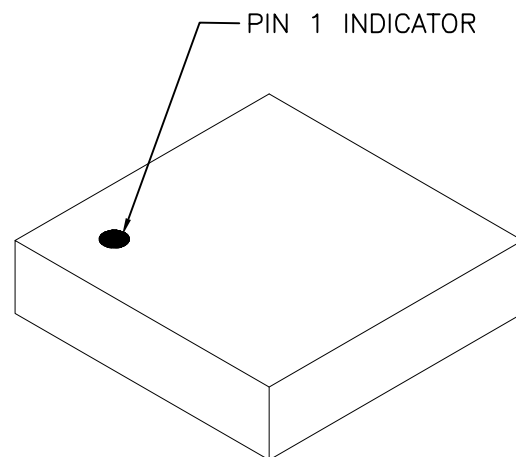
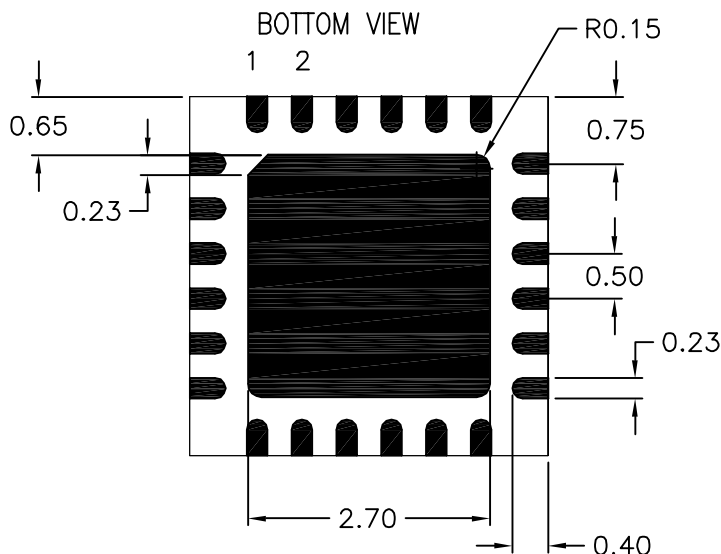
REVISIONS				
LTR	DESCRIPTION	EDCN	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	MASS ECN UPDATE	10/4/06	HALL

TOP VIEW
18 17 16 15 14 13



SEE BOTTOM VIEW FOR
RECOMMENDED LAND PATTERN
DIMENSIONS

BOTTOM VIEW



ISOMETRIC VIEW

NOTES:

- THIS PACKAGE CONFORMS TO JEDEC MO220 - VGGD-5 VARIATION
- ALL DIMENSIONS ARE IN MILLIMETERS AND TYPICAL.
- PACKAGE BASE MATERIAL: COPPER

= EXPOSED METAL CONTACT PADS:
 Ni/Pd/Au PPF OR MATT Sn
- DIE PADDLE SIZE: 2.7 X 2.7
- SMT EXPOSURE: THIS DEVICE WILL WITHSTAND EXPOSURE TO TEMPERATURES OF 240°C MAXIMUM FOR DWELL TIME OF 10 SECONDS MAXIMUM.

MKT-MLP24DrevA

APPROVALS		DATE		FAIRCHILD SEMICONDUCTOR		TYNGSBORO, MA. 01879 300 POTASH HILL RD.	
DRAWN	MARC DUBOIS	1/7/05		24LD,MLP,QUAD,JEDEC MO220,4MM SQUARE		MKT-MLP24D	
DFTG. CHK.							
ENGR. CHK.							
PROJECTION		SCALE		SIZE		DRAWING NUMBER	
INCH (MM)		N/A		N/A		REV	
		DO NOT SCALE DRAWING		SHEET 1 of 1			